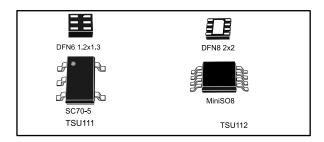


TSU111, TSU112

Nanopower (900 nA), high accuracy (150 µV) 5 V CMOS operational amplifier

Datasheet - production data



Features

- Sub-micro ampere current consumption: lcc = 900 nA typ. at 25 °C
- Low offset voltage: 150 μV max. at 25 °C, 235 μV max. over full temperature range (-40 to 85 °C)
- Low noise over 0.1 to 10 Hz bandwidth: 3.6 μVpp
- Low supply voltage: 1.5 V to 5.5 V
- Rail-to-rail input and output
- Gain bandwidth product: 11.5 kHz typ.
- Low input bias current: 10 pA max. at 25 °C
- High tolerance to ESD: 4 kV HBM

Benefits

- More than 25 years of typical equivalent lifetime supplied by a 220 mA.h CR2032 coin type Lithium battery
- High accuracy without calibration
- Tolerance to power supply transient drops

Related products

- See TSU101, TSU102 and TSU104 for further power savings
- See *TSZ121*, *TSZ122* and *TSZ124* for increased accuracy

Applications

- Gas sensors: CO, O₂, and H₂S
- Alarms: PIR sensors
- Signal conditioning for energy harvesting and wearable products
- Ultra long-life battery-powered applications
- Battery current sensing
- Active RFID tags

Description

The TSU111, TSU112 operational amplifiers (op-amp) offer an ultra low-power consumption per channel of 900 nA typical and 1.2 μ A maximum when supplied by 3.3 V. Combined with a supply voltage range of 1.5 V to 5.5 V, these features allow the TSU11x to be efficiently supplied by a coin type Lithium battery or a regulated voltage in low-power applications.

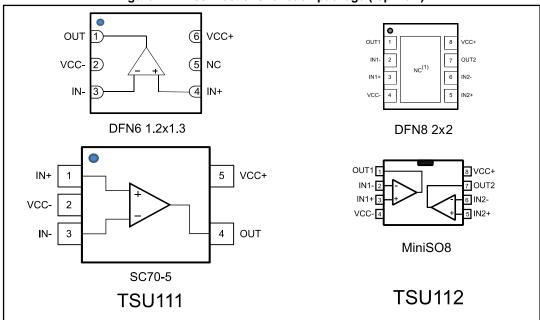
The high accuracy of 150 μ V max. and 11.5 kHz gain bandwidth make the TSU11x ideal for sensor signal conditioning, battery supplied, and portable applications.

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1 Package pin connections

Figure 1: Pin connections for each package (top view)



1. The exposed pad of the DFN8 2x2 can be connected to $V_{\text{CC-}}$ or left floating.

2 Absolute maximum ratings and operating conditions

Table 1: Absolute maximum ratings (AMR)

Symbol	Parameter		Value	Unit
Vcc	Supply voltage (1)		6	
Vid	Differential input voltage (2)		±Vcc	V
V_{in}	Input voltage (3)		(V_{CC-}) - 0.2 to (V_{CC+}) + 0.2	
lin	Input current (4)	10	mA	
T _{stg}	Storage temperature	-65 to 150	°C	
Tj	Maximum junction temperature	150		
		DFN6 1.2x1.3	232	
D	Thermal resistance junction-to-	SC70-5	205	°C/W
R _{thja}	ambient (5)(6)	DFN8 2x2	57	C/VV
		190		
	HBM: human body model (7)	4000	V	
ESD	CDM: charged device model (8)	1500	V	
	Latch-up immunity (9)	200	mA	

Notes:

Table 2: Operating conditions

Symbol	Parameter	Value	Unit					
Vcc	Supply voltage	1.5 to 5.5	\ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \ \					
V _{icm}	Common-mode input voltage range	(Vcc-) - 0.1 to (Vcc+) + 0.1	V					
T _{oper}	Operating free-air temperature range	-40 to 85	°C					



⁽¹⁾All voltage values, except the differential voltage are with respect to the network ground terminal.

⁽²⁾The differential voltage is the non-inverting input terminal with respect to the inverting input terminal.

 $^{^{(3)}(\}mbox{V}_{\mbox{\footnotesize{CC+}}})$ - $\mbox{V}_{\mbox{\footnotesize{in}}}$ must not exceed 6 V, $\mbox{V}_{\mbox{\footnotesize{in}}}$ - (Vcc-) must not exceed 6 V.

⁽⁴⁾The input current must be limited by a resistor in-series with the inputs.

⁽⁵⁾Rth are typical values.

⁽⁶⁾Short-circuits can cause excessive heating and destructive dissipation.

⁽⁷⁾Related to ESDA/JEDEC JS-001 Apr. 2010.

⁽⁸⁾Related to JEDEC JESD22-C101-E Dec. 2009.

⁽⁹⁾Related to JEDEC JESD78C Sep. 2010.

3 Electrical characteristics

Table 3: Electrical characteristics at (VCC+) = 1.8 V with (VCC-) = 0 V, Vicm = VCC/2, Tamb = 25 °C, and RL = 1 $M\Omega$ connected to VCC/2 (unless otherwise specified)

Symbol	Parameter	Conditions		Тур.	Max.	Unit	
DC perfo	rmance		•				
		T = 25 °C			150		
V_{io}	Input offset voltage	-40 °C < T< 85 °C			235	μV	
ΔV _{io} /ΔΤ	Input offset voltage drift	-40 °C < T< 85 °C			1.4	μV/°C	
ΔV_{io}	Long-term input offset voltage drift	T = 25 °C ⁽¹⁾		TBD		μV/√month	
1.	Input offeet ourrent (2)	T = 25 °C		1	10		
l _{io}	Input offset current (2)	-40 °C < T< 85 °C			50	nΛ	
	Input bigg ourrent (2)	T = 25 °C		1	10	pА	
l _{ib}	Input bias current (2)	-40 °C < T< 85 °C			50		
	Common mode rejection	T = 25 °C	76	107			
CMR	ratio, 20 log ($\Delta V_{icm}/\Delta V_{io}$), $V_{icm} = 0$ to 1.8 V	-40 °C < T< 85 °C	71			dB	
	Large signal voltage gain,	R _L = 100 kΩ, T = 25 °C	95	120		uБ	
A _{vd}	$V_{out} = 0.2 \text{ V to}$ (Vcc+) - 0.2 V	R _L = 100 kΩ, -40 °C < T< 85 °C	90				
Vон	High-level output voltage,	R _L = 10 kΩ, T = 25 °C		10	25		
Vol	(drop from vcc+)	R _L = 10 kΩ, -40 °C < T< 85 °C			40	mV	
		$R_L = 10 \text{ k}\Omega, T = 25^{\circ}\text{C}$		8	25	IIIV	
VOL	Low-level output voltage	R _L = 10 kΩ, -40 °C < T< 85 °C			40		
	Output sink current,	T = 25 °C	2.8	5			
1	$V_{out} = V_{CC}$, $V_{ID} = -200 \text{ mV}$	-40 °C < T< 85 °C	1.5			mA	
lout	Output source current,	T = 25 °C	2	4		IIIA	
	$V_{out} = 0 \text{ V}, V_{ID} = 200 \text{ mV}$	-40 °C < T< 85 °C	1.5				
	Supply current (per	T = 25 °C		900	1200		
Icc	channel), no load, V _{out} = V _{CC} /2	-40 °C < T< 85 °C			1480	nA	
AC perfo	rmance						
GBP	Gain bandwidth product			10			
Fu	Unity gain frequency	D 4440 0 00 5		8		kHz	
Фт	Phase margin	$R_L = 1 M\Omega$, $C_L = 60 pF$		60		degrees	
Gm	Gain margin			10		dB	
SR	Slew rate (10% to 90%)	$R_L = 1 \text{ M}\Omega, C_L = 60 \text{ pF},$ $V_{out} = 0.3 \text{ V to (Vcc+)} - 0.3 \text{ V}$		2.5		V/ms	
Сn	Equivalent input noise voltage	f = 100 Hz		220		nV/√Hz	
∫en	Low-frequency, peak-to-peak input noise	Bandwidth: f = 0.1 to 10 Hz		3.8		μV_{pp}	



Symbol	Parameter	Conditions		Тур.	Max.	Unit
t _{rec}	Overload recovery time	100 mV from rail in comparator, $R_L = 100 \text{ k}\Omega$, $V_{ID} = \pm 1 \text{ V}$, -40 °C < T< 85 °C		325		μs

Notes:

Table 4: Electrical characteristics at (VCC+) = 3.3 V with (VCC-) = 0 V, Vicm = VCC/2, Tamb = 25 °C, and RL = 1 M Ω connected to VCC/2 (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
DC perfo	rmance		<u>'</u>	'		
	land offert with the	T = 25 °C			150	\/
V_{io}	Input offset voltage	-40 °C < T< 85 °C			235	μV
$\Delta V_{io}/\Delta T$	Input offset voltage drift	-40 °C < T< 85 °C			1.4	μV/°C
ΔV_{io}	Long-term input offset voltage drift	T = 25 °C ⁽¹⁾		TBD		μV/√month
	Input offset surrent (2)	T = 25 °C		1	10	
l _{io}	Input offset current (2)	-40 °C < T< 85 °C			50	 Λ
L.	Input bias current (2)	T = 25 °C		1	10	pΑ
l _{ib}	input bias current (=)	-40 °C < T< 85 °C			50	
	Common mode rejection ratio,	T = 25 °C	81	110		
CMR	$\begin{array}{c} 20 \ log \ (\Delta V_{icm}/\Delta V_{io}), \\ V_{icm} = 0 \ to \ 3.3 \ V \end{array}$	-40 °C < T< 85 °C	76			dB
_	Large signal voltage gain, V _{out} = 0.2 V to (V _{CC+}) - 0.2 V	R _L = 100 kΩ, T = 25 °C	105	130		ub
A _{vd}		R _L = 100 kΩ, -40 °C < T< 85 °C	105			
Vон	High-level output voltage,	R _L = 10 kΩ, T = 25 °C		10	25	
VOH	(drop from V _{CC} +)	$R_L = 10 \text{ k}\Omega, -40 \text{ °C} < T < 85 \text{ °C}$			40	mV
Vol	Low-level output voltage	R _L = 10 kΩ, T = 25 °C		7	25	IIIV
VOL	Low-level output voltage	$R_L = 10 \text{ k}\Omega, -40 \text{ °C} < T < 85 \text{ °C}$			40	
	Output sink current,	T = 25 °C	12	22		
1.	$V_{out} = V_{CC}$, $V_{ID} = -200 \text{ mV}$	-40 °C < T< 85 °C	6			mA
l _{out}	Output source current,	T = 25 °C	9	18		IIIA
	$V_{out} = 0 \text{ V}, V_{ID} = 200 \text{ mV}$	-40 °C < T< 85 °C	5			
laa	Supply current (per channel),	T = 25 °C		900	1200	nA
Icc	no load, V _{out} = V _{CC} /2	-40 °C < T< 85 °C			1480	IIA
AC perfo	rmance					
GBP	Gain bandwidth product			11		kHz
Fu	Unity gain frequency	$R_L = 1 M\Omega$, $C_L = 60 pF$		10		K⊓Z
Фт	Phase margin	$ C_L = 1 \text{ IVIZ}, C_L = 60 \text{ pr}$		60		degrees
Gm	Gain margin			7		dB

⁽¹⁾Typical value is based on the Vio drift observed after 1000h at 85 °C extrapolated to 25 °C using the Arrhenius law and assuming an activation energy of 0.7 eV. The operational amplifier is aged in follower mode configuration

⁽²⁾Guaranteed by design

Symbol	Parameter	Parameter Conditions		Тур.	Max.	Unit
SR	Slew rate (10% to 90%)	$R_L = 1 \text{ M}\Omega, C_L = 60 \text{ pF},$ $V_{out} = 0.3 \text{ V to (V}_{CC+}) - 0.3 \text{ V}$		2.5		V/ms
en	Equivalent input noise voltage	f = 100 Hz		220		nV/√Hz
∫e _n	Low-frequency, peak-to-peak input noise	Bandwidth: f = 0.1 to 10 Hz		3.7		μV_{pp}
t _{rec}	Overload recovery time	100 mV from rail in comparator, R _L = 100 k Ω , V _{ID} = ± 1 V, -40 °C < T< 85 °C		630		μs

Notes:

Table 5: Electrical characteristics at (VCC+) = 5 V with (VCC-) = 0 V, Vicm = VCC/2, Tamb = 25 °C, and RL = 1 $M\Omega$ connected to VCC/2 (unless otherwise specified)

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit
DC perfo	rmance		•	'		1
Vio	Input offeet veltage	T = 25 °C			150	/
Vio	Input offset voltage	-40 °C < T< 85 °C			235	μV
$\Delta V_{io}/\Delta T$	Input offset voltage drift	-40 °C < T< 85 °C			1.4	μV/°C
ΔV_{io}	Long-term input offset voltage drift	T = 25 °C ⁽¹⁾		TBD		μV/√month
1.	Input offset current (2)	T = 25 °C		1	10	
l _{io}	input onset current (=)	-40 °C < T< 85 °C			50	 Λ
I	Input bias current (2)	T = 25 °C		1	10	рA
l _{ib}	input bias current	-40 °C < T< 85 °C			50	
	Common mode rejection ratio,	T = 25 °C	90	121		
CMR	$ 20 \log (\Delta V_{icm}/\Delta V_{io}), $ $V_{icm} = 0 \text{ to } 4.4 \text{ V} $	-40 °C < T< 85 °C	90			
	Common mode rejection ratio, 20	T = 25 °C	85	112		
	$\begin{array}{l} log \ (\Delta V_{icm}/\Delta V_{io}), \\ V_{icm} = 0 \ to \ 5 \ V \end{array}$	-40 °C < T< 85 °C	80			dB
	Supply voltage rejection ratio,	T = 25 °C	92	116		
SVR	Vcc = 1.5 to 5.5 V, V _{icm} = 0 V	-40 °C < T< 85 °C	84			
	Large signal voltage gain,	R _L = 100 kΩ, T = 25 °C	105	135		
A_{vd}	$V_{out} = 0.2 \text{ V to } (V_{CC+}) - 0.2 \text{ V}$	R _L = 100 kΩ, -40 °C < T< 85 °C	101			
	High-level output voltage,	$R_L = 10 \text{ k}\Omega, T = 25 \text{ °C}$		10	25	
V _{OH}	(drop from V _{CC} +)	R _L = 10 kΩ, -40 °C < T< 85 °C			40	mV
V _{OL}	Low-level output voltage	R _L = 10 kΩ, T = 25°C		7	25	
VOL		R _L = 10 kΩ, -40 °C < T< 85 °C			40	

 $^{^{(1)}}$ Typical value is based on the Vio drift observed after 1000h at 85 °C extrapolated to 25 °C using the Arrhenius law and assuming an activation energy of 0.7 eV. The operational amplifier is aged in follower mode configuration

⁽²⁾Guaranteed by design

Electrical characteristics

TSU111, TSU112

Symbol	Parameter	Conditions	Min.	Тур.	Max.	Unit	
	Output sink current,	T = 25 °C	30	45			
l _{out}	$V_{\text{out}} = V_{\text{CC}}$, $V_{\text{ID}} = -200 \text{ mV}$	-40 °C < T< 85 °C	15			mA	
	Output source current,	T = 25 °C	25	41			
	$V_{out} = 0 \text{ V}, V_{ID} = 200 \text{ mV}$	-40 °C < T< 85 °C	18				
Icc	Supply current (per channel),	T = 25 °C		950	1350	nA	
ICC	no load, V _{out} = V _{CC} /2	-40 °C < T< 85 °C			1620	IIA	
AC perfo	ormance						
GBP	Gain bandwidth product			11.5		1.11=	
Fu	Unity gain frequency	D 4 MO C 50 75		10		kHz	
Фт	Phase margin	$R_L = 1 \text{ M}\Omega, C_L = 60 \text{ pF}$		60		degrees	
Gm	Gain margin			7		dB	
SR	Slew rate (10% to 90%)	$R_L = 1 \text{ M}\Omega, C_L = 60 \text{ pF},$ $V_{out} = 0.3 \text{ V to } (V_{CC+}) - 0.3 \text{ V}$		2.7		V/ms	
en	Equivalent input noise voltage	f = 100 Hz		200		nV/√Hz	
∫en	Low-frequency, peak-to-peak input noise	Bandwidth: f = 0.1 to 10 Hz		3.6		μV_{pp}	
t _{rec}	Overload recovery time	100 mV from rail in comparator, R_L = 100 kΩ, V_{ID} = ±1 V, -40 °C < T< 85 °C		940		μs	
		V _{in} = -10 dBm, f = 400 MHz		54			
EMIRR	Electromagnetic interference	V _{in} = -10 dBm, f = 900 MHz		79		dB	
EWIKK	rejection ratio (3)	V _{in} = -10 dBm, f = 1.8 GHz		65			
		V _{in} = -10 dBm, f = 2.4 GHz		65			

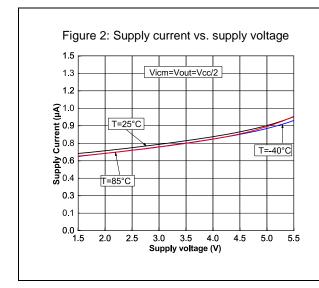
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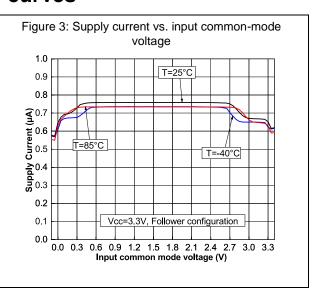
 $^{^{(1)}}$ Typical value is based on the Vio drift observed after 1000h at 85 °C extrapolated to 25 °C using the Arrhenius law and assuming an activation energy of 0.7 eV. The operational amplifier is aged in follower mode configuration.

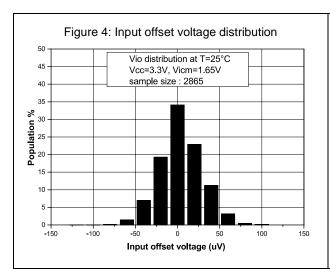
⁽²⁾Guaranteed by design.

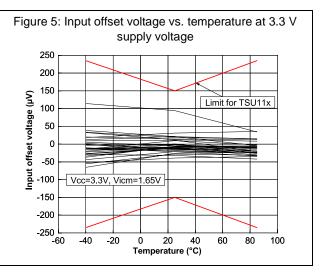
⁽³⁾Based on evaluations performed only in conductive mode on the TSU111ICT.

4 Electrical characteristic curves









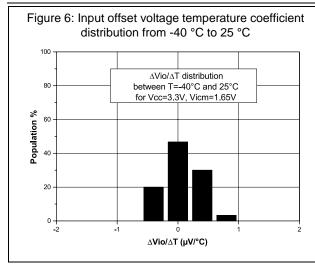


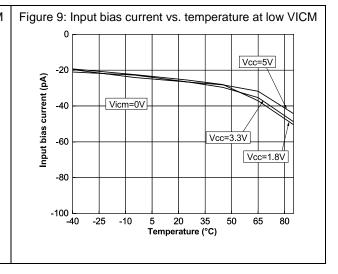
Figure 7: Input offset voltage temperature coefficient distribution from 25 °C to 85 °C

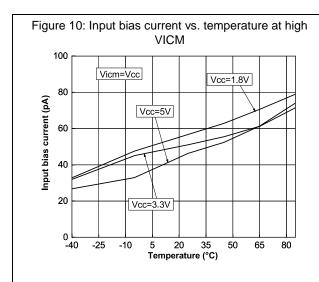
AVIO/AT distribution between T=25°C and 85°C for Vcc=3.3V, Vicm=1.65V

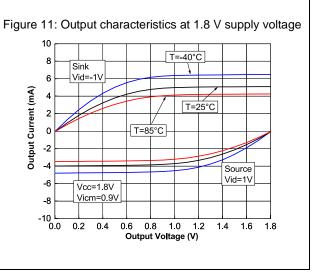
AVIO/AT (µV/°C)

Figure 8: Input bias current vs. temperature at mid VICM

20
Vcc=5V
Vcc=3.3V
Vcc=1.8V
Vcc=1.8V
Vcc=1.8V
Vcc=1.8V
Vcc=1.8V







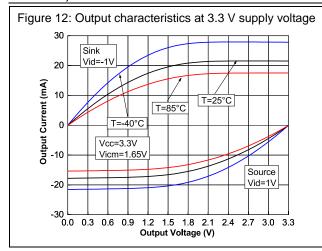
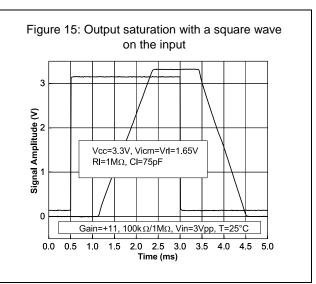
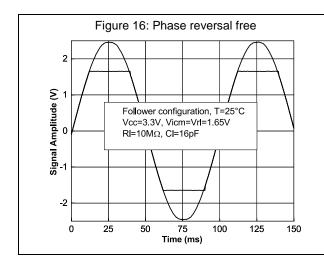
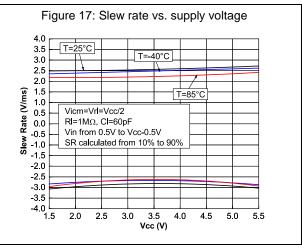


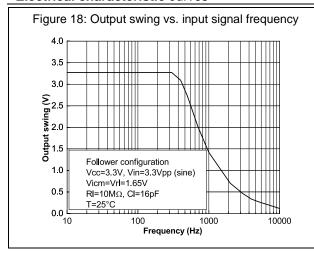
Figure 13: Output characteristics at 5 V supply voltage 40 Vid=-1 30 Output Current (mA)
0 -10
-20 T=85°C T=25°C Vcc=5V Vicm=2.5V -30 Source -40 -50 0.0 0.5 1.0 2.0 2.5 3.0 3.5 4.0 4.5 5.0 Output Voltage (V)

Figure 14: Output saturation with a sine wave on the input 3.275 Vin Vout 3.250 €3.225 3.200 3.200 3.175 3.150 0.125 0.075 Follower configuration, T=25°C, Vcc=3.3V Vin from rail to 200mV from rail, f=10Hz $RI=100k\Omega$ connected to other rail CI=75pF (+1M Ω scope probe to rail) 0.050 0.025 Vout Vin 0.000 10 20 25 30 35 15 45 Time (ms)









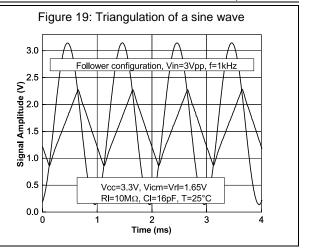


Figure 20: Large signal response at 3.3 V supply voltage

Pollower configuration, T=25°C

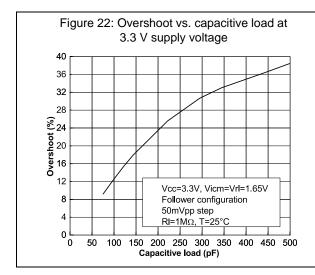
Follower configuration, T=25°C

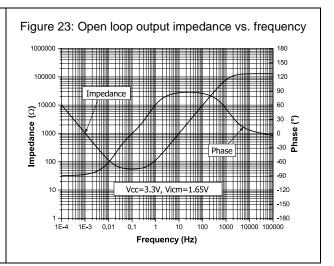
Vcc=3.3V
Vicm=Vrl=1.65V
Rl=10MΩ, Cl=16pF

0 1 2 3 4 5 6 7 8 9 10

Time (ms)

Figure 21: Small signal response at 3.3 V supply voltage Follower configuration, T=25°C 25 20 Signal Amplitude (mV) Vicm=VrI=1.65V RI=1M Ω , CI=75pF -20 -25 -30 -35 └─ 0.0 0.1 0.2 0.3 0.4 0.5 0.6 0.7 0.8 0.9 Time (ms)





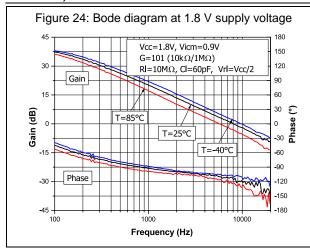
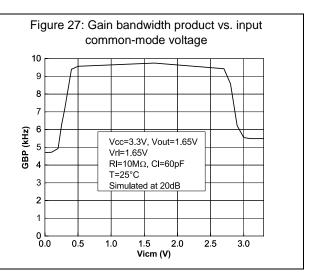
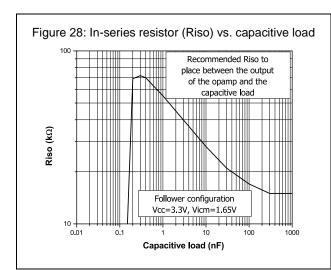
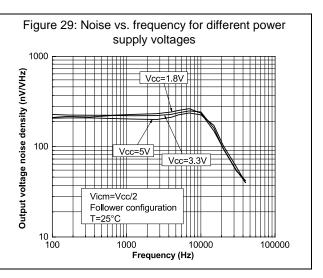


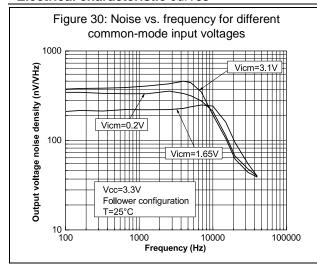
Figure 25: Bode diagram at 3.3 V supply voltage Vcc=3.3V, Vicm=1.65V $G=101 (10k\Omega/1M\Omega)$ 120 RI=10M Ω , CI=60pF, VrI=Vcc/2 90 Gain 60 15 0 0E-Ohase (°) Gain (dB) T=85°C T=25°C T=-40°C Phase -30 -120 -150 -180 -45 100 1000 10000 Frequency (Hz)

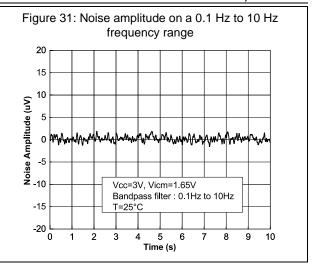
Figure 26: Bode diagram at 5 V supply voltage Vcc=5V, Vicm=2.5V $G=101 (10k\Omega/1M\Omega)$ $RI=10M\Omega$, CI=60pF, VrI=Vcc/2Gain 15 60 T=85°C 30 Gain (dB) 0 30 Phase (T=25°C T=-40°C -60 -90 Phase -120 -150 -180 100 1000 10000 Frequency (Hz)











5 Application information

5.1 Nanopower applications

The TSU11x can operate from 1.5 V to 5.5 V. The parameters are fully specified at 1.8 V, 3.3 V, and 5 V supply voltages and are very stable in the full $V_{\rm CC}$ range. Additionally, the main specifications are guaranteed on the industrial temperature range from -40 to 85 °C. The estimated lifetime of the TSU11x exceeds 25 years if supplied by a CR2032 battery (see *Figure 32: "CR2032 battery"*).



Figure 32: CR2032 battery

5.1.1 Schematic optimization aiming at nanopower

To benefit from the full performance of the TSU11x, the impedances must be maximized so that current consumption is not lost where it is not required.

For example, an aluminum electrolytic capacitance can have significantly high leakage. This leakage may be greater than the current consumption of the op-amp. For this reason, ceramic type capacitors are preferred.

For the same reason, big resistor values should be used in the feedback loop. However, there are two main limitations to be considered when choosing a resistor.

- 1. Noise generated: a 100 k Ω resistor generates 40 nV/ \sqrt{Hz} , a bigger resistor value generates even more noise.
- 2. Leakage on the PCB: leakage can be generated by moisture. This can be improved by using a specific coating process on the PCB.

5.1.2 PCB layout considerations

For correct operation, it is advised to add 10 nF decoupling capacitors as close as possible to the power supply pins.

Minimizing the leakage from sensitive high impedance nodes on the inputs of the TSU11x can be performed with a guarding technique. The technique consists of surrounding high impedance tracks by a low impedance track (the ring). The ring is at the same electrical potential as the high impedance node.

Therefore, even if some parasitic impedance exists between the tracks, no leakage current can flow through them as they are at the same potential (see *Figure 33: "Guarding on the PCB"*).

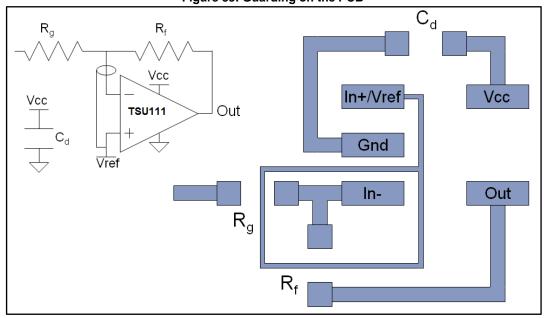


Figure 33: Guarding on the PCB

5.2 Rail-to-rail input

The TSU11x is built with two complementary PMOS and NMOS input differential pairs. Thus, the device has a rail-to-rail input, and the input common mode range is extended from (V_{CC-}) - 0.1 V to (V_{CC+}) + 0.1 V.

The TSU11x has been designed to prevent phase reversal behavior.

5.3 Input offset voltage drift overtemperature

The maximum input voltage drift variation overtemperature is defined as the offset variation related to the offset value measured at 25 °C. The operational amplifier is one of the main circuits of the signal conditioning chain, and the amplifier input offset is a major contributor to the chain accuracy. The signal chain accuracy at 25 °C can be compensated during production at application level. The maximum input voltage drift over temperature enables the system designer to anticipate the effect of temperature variations.

The maximum input voltage drift over temperature is computed using *Equation 1*.

Equation 1

$$\frac{\Delta V_{io}}{\Delta T} = \text{max} \left| \frac{V_{io}(T) - V_{io}(25 \, ^{\circ}\text{C})}{T - 25 \, ^{\circ}\text{C}} \right|$$

Where T = -40 °C and 85 °C.

The TSU11x datasheet maximum values are guaranteed by measurements on a representative sample size ensuring a C_{pk} (process capability index) greater than 1.3.

5.4 Long term input offset voltage drift

To evaluate product reliability, two types of stress acceleration are used:

- Voltage acceleration, by changing the applied voltage
- Temperature acceleration, by changing the die temperature (below the maximum junction temperature allowed by the technology) with the ambient temperature.

The voltage acceleration has been defined based on JEDEC results, and is defined using *Equation 2*.

Equation 2

$$A_{FV} = e^{\beta \cdot (V_S - V_U)}$$

Where:

AFV is the voltage acceleration factor

 β is the voltage acceleration constant in 1/V, constant technology parameter (β = 1)

Vs is the stress voltage used for the accelerated test

V_∪ is the voltage used for the application



The temperature acceleration is driven by the Arrhenius model, and is defined in *Equation 3*.

Equation 3

$$A_{FT} = e^{\frac{E_a}{k} \cdot \left(\frac{1}{T_U} - \frac{1}{T_S}\right)}$$

Where:

AFT is the temperature acceleration factor

Ea is the activation energy of the technology based on the failure rate

k is the Boltzmann constant (8.6173 x 10⁻⁵ eV.K⁻¹)

 T_U is the temperature of the die when V_U is used (°K)

Ts is the temperature of the die under temperature stress (°K)

The final acceleration factor, A_F , is the multiplication of the voltage acceleration factor and the temperature acceleration factor (*Equation 4*).

Equation 4

$$A_F = A_{FT} \times A_{FV}$$

 A_F is calculated using the temperature and voltage defined in the mission profile of the product. The A_F value can then be used in *Equation 5* to calculate the number of months of use equivalent to 1000 hours of reliable stress duration.

Equation 5

Months =
$$A_F \times 1000 \text{ h} \times 12 \text{ months} / (24 \text{ h} \times 365.25 \text{ days})$$

To evaluate the op amp reliability, a follower stress condition is used where V_{CC} is defined as a function of the maximum operating voltage and the absolute maximum rating (as recommended by JEDEC rules).

The V_{io} drift (in μV) of the product after 1000 h of stress is tracked with parameters at different measurement conditions (see *Equation 6*).

Equation 6

$$V_{CC} = maxV_{op} \text{ with } V_{icm} = V_{CC}/2$$

The long term drift parameter (ΔV_{io}), estimating the reliability performance of the product, is obtained using the ratio of the V_{io} (input offset voltage value) drift over the square root of the calculated number of months (*Equation* 7).

Equation 7

$$\Delta V_{io} = \frac{V_{io} drift}{\sqrt{(month s)}}$$

Where V_{io} drift is the measured drift value in the specified test conditions after 1000 h stress duration.

5.5 Using the TSU11x with sensors

The TSU11x has MOS inputs, thus input bias currents can be guaranteed down to 10 pA maximum at ambient temperature. This is an important parameter when the operational amplifier is used in combination with high impedance sensors.

The TSU11x is perfectly suited for trans-impedance configuration. This configuration allows a current to be converted into a voltage value with a gain set by the user. It is an ideal choice for portable electrochemical gas sensing or photo/UV sensing applications. The TSU11x, using trans-impedance configuration, is able to provide a voltage value based on the physical parameter sensed by the sensor.

5.5.1 Electrochemical gas sensors

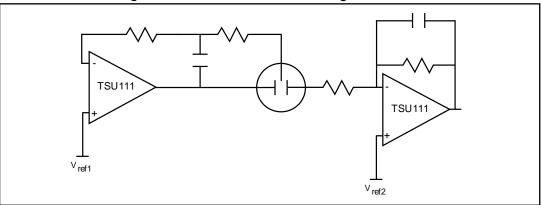
The output current of electrochemical gas sensors is generally in the range of tens of nA to hundreds of μ A. As the input bias current of the TSU11x is very low (see *Figure 8*, *Figure 9*, and *Figure 10*) compared to these current values, the TSU11x is well adapted for use with the electrochemical sensors of two or three electrodes. *Figure 35: "Potentiostat schematic using the TSU111"* shows a potentiostat (electronic hardware required to control a three electrode cell) schematic using the TSU11x. In such a configuration, the devices minimize leakage in the reference electrode compared to the current being measured on the working electrode.

Another great advantage of TSU11x versus the competition is its low noise for low frequencies (3.6 μ Vpp over 0.1 to 10 Hz), and low input offset voltage of 150 μ V max. These improved parameters for the same power consumption allow a better accuracy.

Sensor: electrochemical photodiode/UV

Figure 34: Trans-impedance amplifier schematic

Figure 35: Potentiostat schematic using the TSU111



5.6 Fast desaturation

When the TSU11x goes into saturation mode, it takes a short period of time to recover, typically 630 μ s. When recovering after saturation, the TSU11x does not exhibit any voltage peaks that could generate issues (such as false alarms) in the application (see *Figure 14*).

We can observe that this circuit still exhibits good gain even close to the rails i.e. A_{vd} greater than 105 dB for V_{cc} = 3.3 V with V_{out} varying from 200 mV up to a supply voltage minus 200 mV. With a trans-impedance schematic, a voltage reference can be used to keep the signal away from the supply rails.

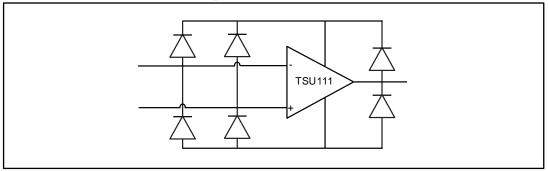
5.7 Using the TSU11x in comparator mode

The TSU11x can be used as a comparator. In this case, the output stage of the device always operates in saturation mode. In addition, *Figure 3* shows that the current consumption is not higher and even decreases smoothly close to the rails. The TSU11x is obviously an operational amplifier and is therefore optimized for use in linear mode. We recommend using the TS88 series of nanopower comparators if the primary function is to perform a signal comparison only.

5.8 ESD structure of the TSU11x

The TSU11x is protected against electrostatic discharge (ESD) with dedicated diodes (see *Figure 36: "ESD structure"*). These diodes must be considered at application level especially when signals applied on the input pins go beyond the power supply rails (V_{CC+}) or (V_{CC-}).

Figure 36: ESD structure



Current through the diodes must be limited to a maximum of 10 mA as stated in *Table 1: "Absolute maximum ratings (AMR)"*. A serial resistor on the inputs can be used to limit this current.

5.9 EMI robustness of nanopower devices

Nanopower devices exhibit higher impedance nodes and consequently they are more sensitive to EMI. To improve the natural robustness of the TSU11x device, we recommend to add three capacitors of around 22 pF each between the two inputs, and between each input and ground. These capacitors lower the impedance of the input at high frequencies and therefore reduce the impact of the radiation.

6 Package information

In order to meet environmental requirements, ST offers these devices in different grades of ECOPACK® packages, depending on their level of environmental compliance. ECOPACK® specifications, grade definitions and product status are available at: **www.st.com**. ECOPACK® is an ST trademark.

6.1 SC70-5 (or SOT323-5) package information (TSU111)

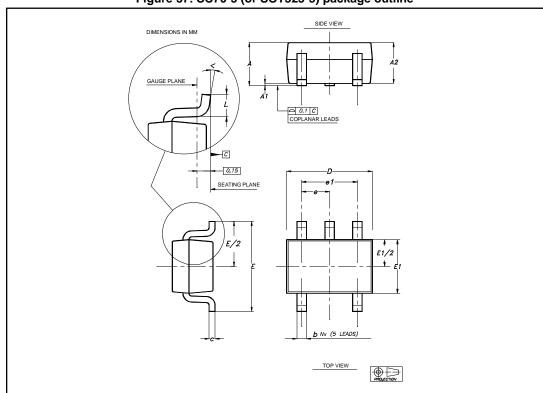


Figure 37: SC70-5 (or SOT323-5) package outline

Table 6: SC70-5 (or SOT323-5) package mechanical data

			Dim	nensions			
Ref.		Millimeters		Inches			
	Min.	Тур.	Max.	Min.	Тур.	Max.	
А	0.80		1.10	0.032		0.043	
A1			0.10			0.004	
A2	0.80	0.90	1.00	0.032	0.035	0.039	
b	0.15		0.30	0.006		0.012	
С	0.10		0.22	0.004		0.009	
D	1.80	2.00	2.20	0.071	0.079	0.087	
Е	1.80	2.10	2.40	0.071	0.083	0.094	
E1	1.15	1.25	1.35	0.045	0.049	0.053	
е		0.65			0.025		
e1		1.30			0.051		
L	0.26	0.36	0.46	0.010	0.014	0.018	
<	0°		8°	0°		8°	

6.2 DFN6 1.2x1.3 package information (TSU111)

Figure 38: DFN6 1.2x1.3 package outline

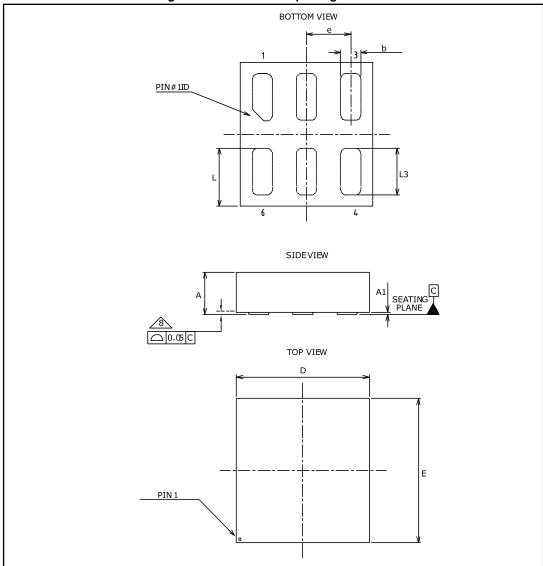


Table 7: DFN6 1.2x1.3 mechanical data

	Dimensions								
Ref.		Millimeters		Inches					
	Min.	Тур.	Max.	Min.	Тур.	Max.			
А	0.31	0.38	0.40	0.012	0.015	0.016			
A1	0.00	0.02	0.05	0.000	0.001	0.002			
b	0.15	0.18	0.25	0.006	0.007	0.010			
С		0.05			0.002				
D		1.20			0.047				
Е		1.30			0.051				
е		0.40			0.016				
L	0.475	0.525	0.575	0.019	0.021	0.023			
L3	0.375	0.425	0.475	0.015	0.017	0.019			

Figure 39: DFN6 1.2x1.3 recommended footprint

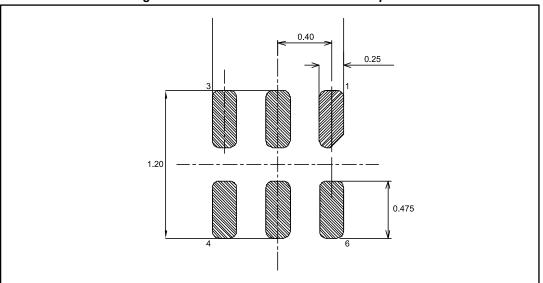


Table 8: DFN6 1.2x1.3 recommended footprint data

Dimensions									
Ref.	Inches								
Α	4.00	0.450							
В	4.00	0.158							
С	0.50	0.020							
D	0.30	0.012							
E	1.00	0.039							
F	0.70	0.028							
G	0.66	0.026							

6.3 MiniSO8 package information (TSU112)

Figure 40: MiniSO8 package outline

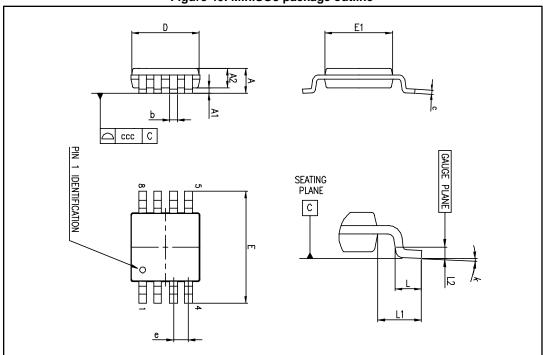


Table 9: MiniSO8 package mechanical data

	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
А			1.1			0.043
A1	0		0.15	0		0.006
A2	0.75	0.85	0.95	0.030	0.033	0.037
b	0.22		0.40	0.009		0.016
С	0.08		0.23	0.003		0.009
D	2.80	3.00	3.20	0.11	0.118	0.126
Е	4.65	4.90	5.15	0.183	0.193	0.203
E1	2.80	3.00	3.10	0.11	0.118	0.122
е		0.65			0.026	
L	0.40	0.60	0.80	0.016	0.024	0.031
L1		0.95			0.037	
L2		0.25			0.010	
k	0°		8°	0°		8°
ccc			0.10			0.004

TSU111, TSU112 Package information

6.4 DFN8 2x2 package information (TSU112)

Figure 41: DFN8 2x2 package outline

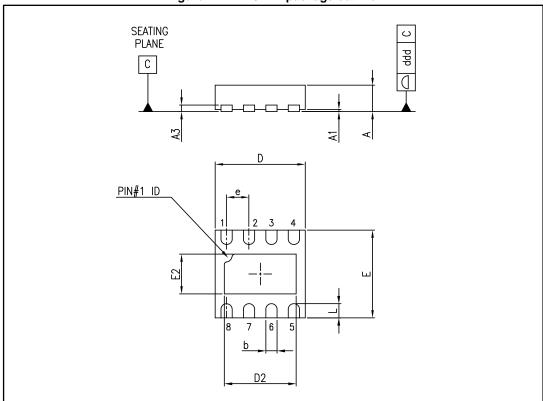
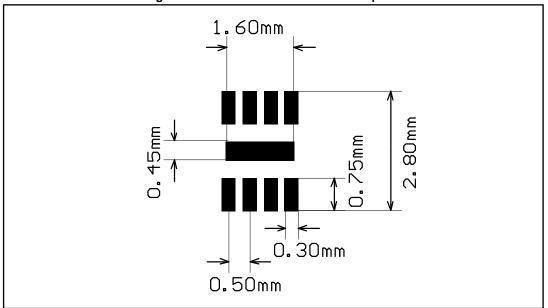


Table 10: DFN8 2x2 package mechanical data

	Dimensions					
Ref.	Millimeters			Inches		
	Min.	Тур.	Max.	Min.	Тур.	Max.
Α	0.51	0.55	0.60	0.020	0.022	0.024
A1			0.05			0.002
А3		0.15			0.006	
b	0.18	0.25	0.30	0.007	0.010	0.012
D	1.85	2.00	2.15	0.073	0.079	0.085
D2	1.45	1.60	1.70	0.057	0.063	0.067
Е	1.85	2.00	2.15	0.073	0.079	0.085
E2	0.75	0.90	1.00	0.030	0.035	0.039
е		0.50			0.020	
L	0.225	0.325	0.425	0.009	0.013	0.017
ddd			0.08			0.003

Figure 42: DFN8 2x2 recommended footprint



7 Ordering information

Table 11: Order code

Order code	Temperature range	Package (1)	Marking	
TSU111IQ1T		DFN6 1.2x1.3	K8	
TSU111ICT	40 °C to 95 °C	SC70-5		
TSU112IQ2T	-40 °C to 85 °C	DFN8 2x2	K07	
TSU112IST		MiniSO8	K37	

Notes:

⁽¹⁾All devices are delivered in tape and reel packing.

Revision history TSU111, TSU112

8 Revision history

Table 12: Document revision history

Date	Revision	Changes
17-Oct-2016	1	Initial release
14-Nov-2016	2	Features: added "rail-to-rail input and output". Description: updated the maximum ultra low-power consumption of TSU111 op amp. Applications: updated Table 5: added EMIRR typ. values Added Section 5.9: "EMI robustness of nanopower devices".
05-Dec-2017	3	Added the part number TSU112 and the relative package information MiniSO8 and DFN8 2x2.

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